

EPS 2821

LOW VISCOSITY HIGH HDT POTTING & ADHESIVE EPOXY SYSTEM

DESCRIPTION

EPS 2821 is an extremely low viscosity version of EPS 2820 for processing at lower temperatures with void free casting. EPS 2821 is designed for applications in potting, casting, laminating, filament winding, etc.

FEATURES

Unfilled
Rigid 80 D
Excellent Electrical Properties
Extremely Low Viscosity
Good Hydrolytic Stability
Good HDT

Liquid

<u>Properties</u>	<u>Epoxy 260A</u>	<u>AMN 370B</u>	<u>Mixed</u>
Appearance	Amber Liquid	Amber Liquid	Amber Liquid
Viscosity (cps)	400-1,500(77F)	100-200(77F)	300-1,000(77F)
Density (lbs/gal)	9.50-9.70	9.00-9.20	9.40-9.60

PHYSICAL PROPERTIES

Hardness, Shore D	80
Dielectric Constant (KHZ)	3.00
Dissipation Factor (KHZ)	0.015
Volume Resistivity · ohm-cm	1.20 X 10 ¹⁶
Moisture Resistance 3 Weeks Immersion H ₂ O	
Weight Gain	0.8%
Impact Strength, Ft. Lbs/In	.80
Compressive Strength (psi)	32,000
Tensile Strength	10,000
Elongation, %	5.00
HDT Deg F	275

EPS 2821 cont:

PROCESSING PARAMETERS

Process Epoxy resin 260A and Amine Hardener 370B between 77 and 200 Deg F.

Mold Temperature: 77 to 200 degrees F.

Mix Ratio: 100 parts Resin 260A to 16.0 parts Amine 370B by weight.

Degas mixture if possible.

Pot Life: (200g mass) (77 Deg F) 80 to 120 minutes.

Demold: 4-5 hours. Demold time maybe shortened by using higher mold and process temperatures.

Post Cure: 2 hours @ 250 Deg F plus 24 hours at 77 Deg F.

STORAGE

Systems should be stored unopened in air tight containers at 60-90 degrees F.

HANDLING PRECAUTIONS

For complete and updated health and safety information, read the MATERIAL SAFETY DATA SHEETS. Do not handle or use until the MATERIAL SAFETY DATA SHEET has been read and understood.